

Material Composition Specification

MELF Case

Available with Pb (lead)-free plating*



Device average mass150 mg
Fluctuation margin +/-10%

Device part	Substance	mass (mg)
active device	doped Si	0.25
leadframe	Fe Cu Ni	41.6 15.5 36.9
*plating	SnPb20 or Sn (100% tin, Pb-free)	1.15 1.15
glass encapsulation	PbO SiO ₂ K ₂ O	32.7 20.1 1.80

*Specify Lead-free when ordering 100% tin (Pb-free) plating option.